



## Material Content Data Sheet



<b>Sales Product Name</b>				SAK-TC387QP-160F300S AD		<b>Issued</b>		31. January 2019	
<b>MA#</b>				MA003843162					
<b>Package</b>				PG-LFBGA-292-11		<b>Weight*</b>		860.98 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	26.579	3.09	3.09	30871	30871	
wire	noble metal	palladium	7440-05-3	0.017	0.00		20		
	non noble metal	copper	7440-50-8	1.697	0.20	0.20	1972	1992	
encapsulation	organic material	carbon black	1333-86-4	0.700	0.08		813		
	plastics	epoxy resin	-	48.294	5.61		56092		
substrate	inorganic material	silicondioxide	60676-86-0	300.961	34.94	40.63	349557	406462	
	inorganic material	bariumsulfate	7727-43-7	10.803	1.25		12547		
	plastics	acrylic resin	-	12.502	1.45		14521		
	non noble metal	metal hydroxide	-	14.262	1.66		16565		
	inorganic material	amorphous silica	7631-86-9	28.524	3.31		33130		
	plastics	epoxy resin	-	49.826	5.79		57872		
	inorganic material	glass fibre wool	65997-17-3	57.049	6.63		66260		
	non noble metal	copper	7440-50-8	189.158	21.97	42.06	219700	420595	
plating	noble metal	gold	7440-57-5	1.136	0.13		1320		
	non noble metal	nickel	7440-02-0	3.110	0.36	0.49	3612	4932	
solderball	noble metal	silver	7440-22-4	3.921	0.46		4554		
	non noble metal	tin	7440-31-5	108.111	12.56	13.02	125567	130121	
glue	plastics	epoxy resin	-	1.082	0.13		1257		
	noble metal	silver	7440-22-4	3.246	0.38	0.51	3770	5027	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

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